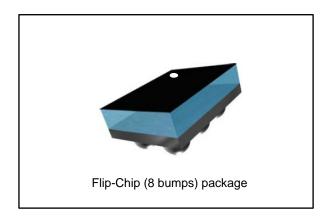


BALF-112X-02D3

50 ohm nominal input / conjugate match balun CC1120, CC1125, 433 MHz, with integrated harmonic filter

Datasheet - production data



Features

- 50 Ω nominal input / conjugate match to CC1120, CC1125, CC1175, CC1200
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance
- Small footprint

Benefits

- Very low profile (< 630 µm thickness)
- High RF performance
- RF BOM and size reduction

Applications

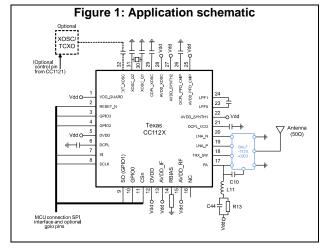
 433 MHz impedance-matched balun filter optimized for Texas Instruments® CC1120, CC1125, CC1175, CC1200 sub-GHz RFICs

Description

STMicroelectronics' BALF-112X-02D3 is an ultra-miniature balun, integrating both matching network and harmonics filter.

Matching impedance has been customized for the CC1120, CC1125, CC1175 and CC1200 transceivers from Texas Instruments.

The device uses STMicroelectronics' IPD technology on a non-conductive glass substrate, which optimizes RF performance.



C10 is a DC block capacitor: 0402/100 pF/50 V

Characteristics BALF-112X-02D3

1 Characteristics

Table 1: Absolute maximum ratings (limiting values)

Cumbal	Dozomotov		l loit		
Symbol	Parameter	Min.	Тур.	Max.	Unit
P _{IN}	Input power RFIN		1	20	dBm
V	ESD ratings MIL STD883C (HBM: C = 100 pF, R = 1.5 Ω , air discharge)	1300	1		<
V _{ESD}	ESD ratings machine model (MM: C = 200 pF, R = 25 W, L = 500 nH)	250	-		V
Top	Operating temperature	-40	-	+85	°C

Table 2: Electrical characteristics and RF performance (T_{amb} = 25 °C) RX balun

Cumbal	Parameter		Value				
Symbol	Farameter	Min.	Тур.	Max.	Unit		
Z _{RX}	Nominal differential impedance		Match to CC112X		Ω		
Z _{ANT}	Antenna impedance		50		Ω		
f	Frequency range (bandwidth)	431		436	MHz		
S21 _{RX-ANT}	Insertion loss in bandwidth	-1.9	-1.7		dB		
S11 _{ANT}	Input return loss in bandwidth		-20	-18	dB		
Phase_imbal	Output phase imbalance	0	1.7	10	0		
Ampl_imbal	Output amplitude imbalance		0.3	1	dB		

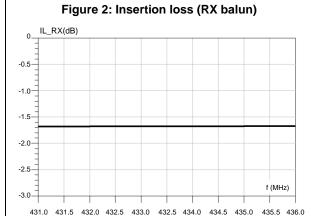
BALF-112X-02D3 Characteristics

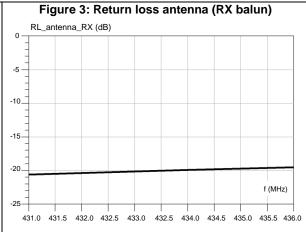
Table 3: Electrical characteristics and RF performance (T_{amb} = 25 °C) TX filter

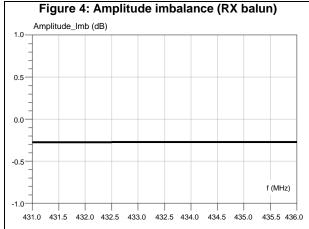
Symbol	Parameter	Test condition		Unit		
Symbol Parameter		Parameter Test condition		Тур.	Max.	Unit
Z _{TX}	Nominal TX impedance			Match to CC112X		Ω
Z _{ANT}	Antenna impedance			50		Ω
f	Frequency range (bandwidth)		431		436	MHz
S21 _{TX-ANT}	Insertion loss in bandwidth		-1.5	-1.3		dB
S11 _{ANT}	Input return loss in bandwidth			-12	-10	dB
		Attenuation at 2 fo		-40	-26	
		Attenuation at 3 fo		-52	-46	
Att		Attenuation at 4 fo		-31	-30	dDm
	Harmonic levels	Attenuation at 5 fo		-35	-32	dBm
		Attenuation at 6 fo		-32	-28	
		Attenuation at 7 fo		-48	-44	

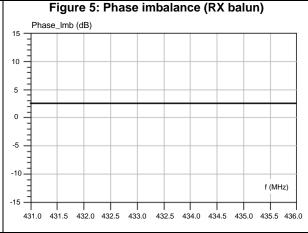
Characteristics BALF-112X-02D3

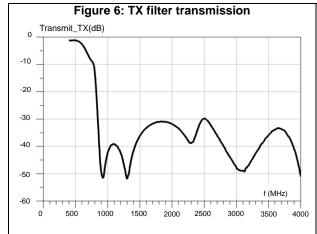
1.1 RF measurement

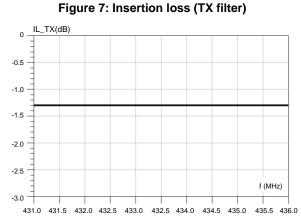




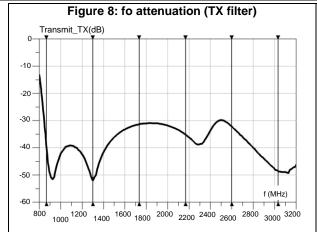


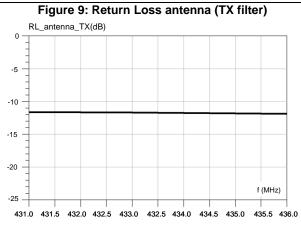






BALF-112X-02D3 Characteristics





Package information BALF-112X-02D3

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

2.1 Flip-Chip CSPG 0.4 package information

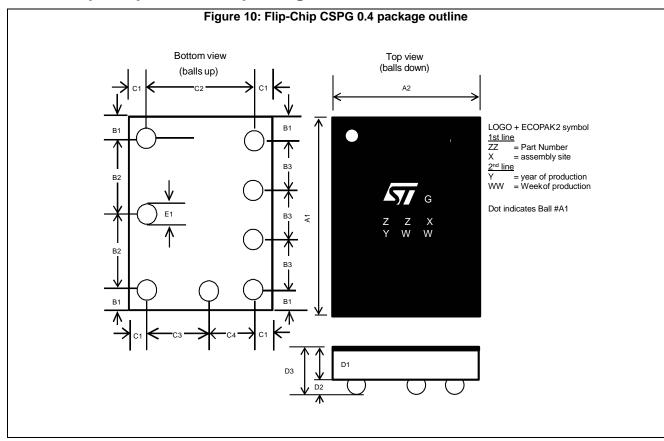


Table 4: Flip-Chip CSPG 0.4 mechanical data

Dimensions	Frequency	A 1	A2	B1	B2	В3	C1	C2	C3	C4	D1	D2	D3	E1
BAL-112X-02D3	433 MHz	1950	1870	225	750	500	223	1424	820	604	425	205	630	255

BALF-112X-02D3 Package information

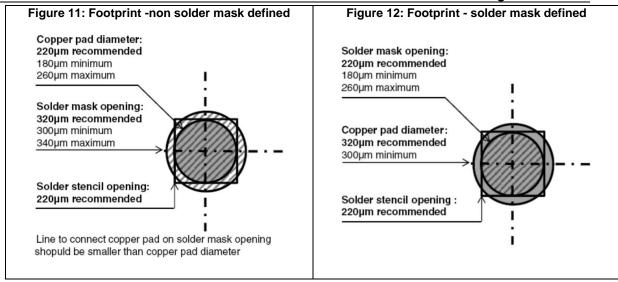


Figure 13: Ball assignment

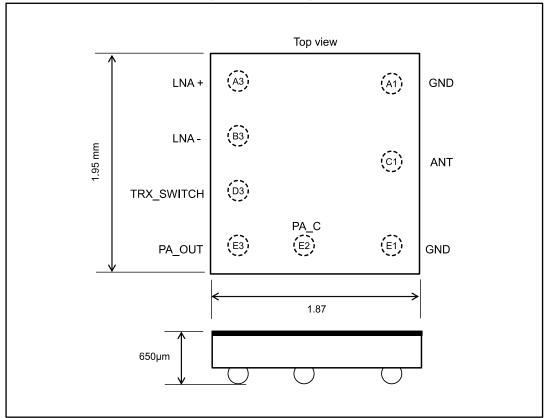
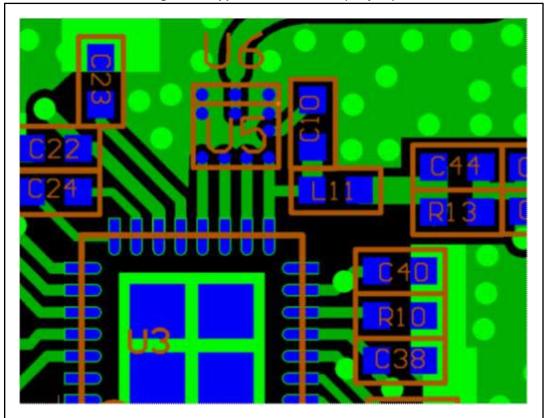


Table 5: Flip-Chip CSPG 0.4 ball description

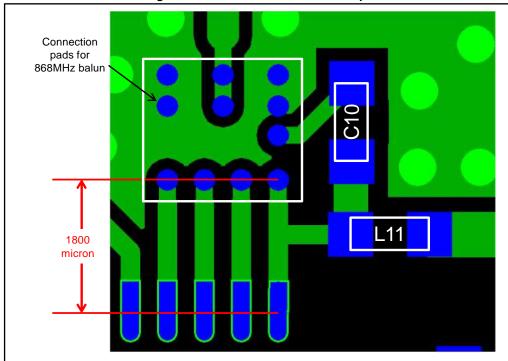
Ball	Name	Designation
A1	GND	Ground
А3	LNA-	Connect to LNA_N
В3	LNA+	Connect to LNA_P
C1	ANT	Connect to antenna
D3	D3 TRX_SW Connect to TRX switch	
E1	GND	Ground
E2	PA_C	Connect to PA output thru C10
E3	PA_OUT	Connect to PA

Figure 14: Application board EVB (4 layers)



BALF-112X-02D3 Package information

Figure 15: Recommended balun land pattern



Center to center distance bettween balun balls to QFN pad is 1.8 mm

Top metal balun pads diamter is 220 micron

Solder mask opening is 340 microns

GND clearance is 178 microns (7 mils)

This land pattern is also compatible with 433 MHz balun that will solder to the second row of pads.

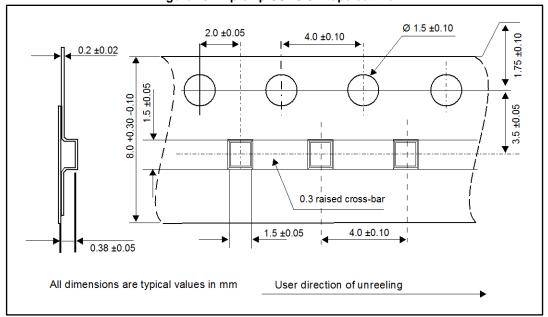
Table 6: Bill of material

Designation	Reference	Value	Package	Comments
L11	LQW15AN10NJ00D	56 nH	0402	Wire wounded
C10		39 pF	0402	50 V
R13		18 Ohms	0402	
C44		56 pF	0402	50 V
U3	CC1121		DFN 5X5	
U6	BALF-112X-02D3		FC 2 X 1.5	433 MHz

Package information BALF-112X-02D3

2.2 Flip-chip CSPG 0.4 packing information

Figure 16: Flip-chip CSPG 0.4 tape outline



BALF-112X-02D3 Ordering information

3 Ordering information

Table 7: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode	
BALF-112X-02D3	TG	Flip-Chip CSPG 0.4	3.94 mg	5000	Tape and reel	

4 Revision history

Table 8: Document revision history

Date	Revision	Changes
07-Jul-2016	1	First issue.
24-Feb-2017	2	Updated front page.

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